

SYSTEM AND METHOD USED IN ATTACHING DIE
FOR BALL GRID ARRAYS

ABSTRACT OF THE DISCLOSURE

5 According to one embodiment of the invention, a method used in attaching die to a substrate includes providing a substrate having a plurality of die attach regions, positioning a dispensing tool having an aperture adjacent a respective one of the die attach regions, positioning the aperture proximate the respective die attach region, dispensing an adhesive through the aperture and onto the respective die attach region, and translating the dispensing tool in a direction perpendicular to a length of the aperture while dispensing the adhesive to form an adhesive region on the respective die attach region. A length of the aperture is greater than a width of the aperture.